

Data Sheet Issue:- 2

Insulated Gate Bi-Polar Transistor Type T0800EB45G

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V _{CES}	Collector – emitter voltage	4500	V
V _{DC link}	Permanent DC voltage for 100 FIT failure rate.	2800	V
Vges	Peak gate – emitter voltage	±20	V

	RATINGS	MAXIMUM LIMITS	UNITS
lc	DC collector current, IGBT	800	А
ICRM	Repetitive peak collector current, t _p =1ms, IGBT	1600	А
IF(DC)	Continuous DC forward current, Diode	800	А
IFRM	Repetitive peak forward current, tp=1ms, Diode	1600	А
IFSM	Peak non-repetitive surge $t_p=10ms$, $V_{RM}=60\%V_{RRM}$, Diode (Note 4)	5.72	kA
IFSM2	Peak non-repetitive surge t _p =10ms, V _{RM} ≤10V, Diode (Note 4)	6.3	kA
Рмах	Maximum power dissipation, IGBT (Note 2)	6.4	kW
PD	Maximum power dissipation, Diode (Note 2)	4.05	kW
(di/dt) _{cr}	Critical diode di/dt (note 3)	2000	A/µs
Tj	Operating temperature range.	-40 to +125	°C
T _{stg}	Storage temperature range.	-40 to +125	°C

Notes: -

- 1) Unless otherwise indicated $T_j = 125^{\circ}C$.
- 2) $T_{sink} = 25^{\circ}C$, double side cooled.
- 3) Maximum commutation loop inductance 400nH.
- 4) Half-sinewave, 125°C T_j initial.



Characteristics

IGBT Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
Vari	Collector – emitter saturation voltage	-	2.75	3.2	$I_C = 800A, V_{GE} = 15V, T_j = 25^{\circ}C$	V
V _{CE(sat)}		-	3.50	3.9	$I_{C} = 800A, V_{GE} = 15V$	V
V _{T0}	Threshold voltage	-	-	1.74		V
rт	Slope resistance	-	-	2.70	Current range: 267A – 800A	mΩ
V _{GE(TH)}	Gate threshold voltage	-	5.2	-	$V_{CE} = V_{GE}, I_C = 85 mA$	V
ICES	Collector – emitter cut-off current		20	50	$V_{CE} = V_{CES}, V_{GE} = 0V$	mA
I _{GES}	Gate leakage current	-	-	±15	$V_{GE} = \pm 20 V$	μA
Cies	Input capacitance	-	135	-	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz	nF
t _{d(on)}	Turn-on delay time	-	1.8	-		μs
tr(V)	Rise time	-	3.3	-	Ic = 800A, V _{CE} =2800V, di/dt=1700A/μs	μs
Qg(on)	Turn-on gate charge	-	5	-	$V_{GE} = \pm 15V$, L _s =200nH	μC
Eon	Turn-on energy	-	6.3	-	$R_{G(ON)}$ = 6.8 Ω , $R_{G(OFF)}$ =10 Ω , C_{GE} = 90nF	J
t _{d(off)}	Turn-off delay time	-	3.0	-	Integral diode used as freewheel diode	μs
t _f (I)	Fall time	-	2.4	-	(Note 3 & 4)	μs
Qg(off)	Turn-off gate charge	-	8	-		μC
Eoff	Turn-off energy	-	3.7	-		J
lsc	Short circuit current	-	2800	-	$\label{eq:VGE} \begin{array}{l} V_{\text{GE}} \mbox{=} \mbox{+} 15 \text{V}, \ V_{\text{CC}} \mbox{=} 2800 \text{V}, \ V_{\text{CEmax}} \mbox{\leq} V_{\text{CES}}, \\ t_p \mbox{\leq} 10 \mbox{\mu s} \end{array}$	А

Diode Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
V _F	Forward voltage	-	3.35	3.6	IF = 800A, Tj =25°C	V
		-	3.50	3.8	IF = 800A	V
VTo	Threshold voltage	-	-	2.05	Current range 267A 900A	V
r⊤	Slope resistance	-	-	2.19	Current range 267A - 800A	mΩ
Irm	Peak reverse recovery current	-	800	-		А
Qrr	Recovered charge	-	1020	-	$I_F = 800A, V_r = 2800V, V_{GE} = -15V,$	μC
trr	Reverse recovery time, 50% chord	-	1.5	-	di/dt=1700A/µs	μs
Er	Reverse recovery energy	-	1.2	-		J

Thermal Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
R _{thJK}	Thermal resistance junction to sink, IGBT	-	-	15.6	Double side cooled	K/kW
		-	-	25.4	Collector side cooled	K/kW
		-	-	40.5	Emitter side cooled	K/kW
R _{thJK}	Thermal resistance junction to sink, Diode	-	-	24.7	Double side cooled	K/kW
		-	-	37.9	Cathode side cooled	K/kW
		-	-	70.8	Anode side cooled	K/kW
F	Mounting force	25	-	35	Note 2	kN
Wt	Weight	-	1.2	-		kg

Notes:-

1) Unless otherwise indicated $T_j=125^{\circ}C$.

 C_{GE} is additional gate – emitter capacitance added to output of gate drive Figures 6 to 9 are obtained using integral diode as freewheeling diode 3)

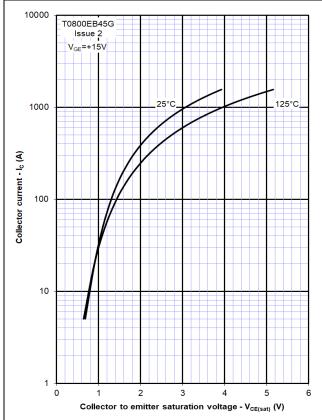
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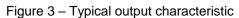
²⁾ Consult application note 2008AN01 for detailed mounting requirements

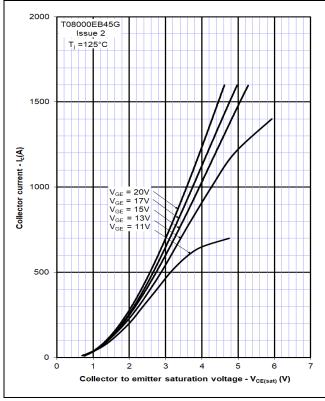


<u>Curves</u>

Figure 1 – Typical collector-emitter saturation voltage characteristics







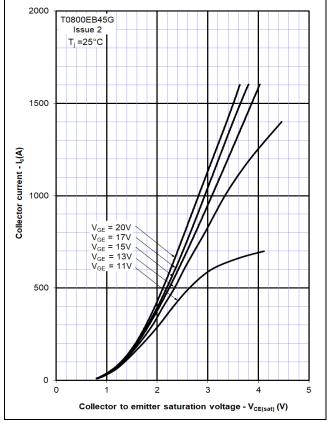


Figure 2 – Typical output characteristic

Figure 4 – Typical turn-on delay time vs gate resistance

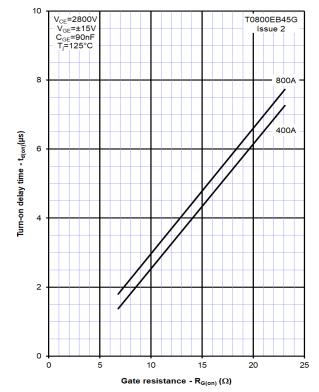
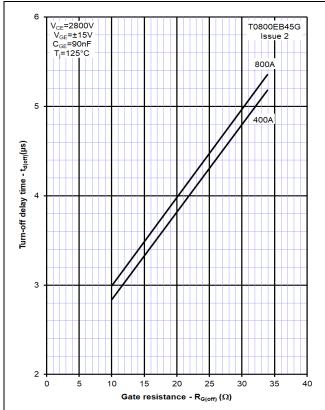
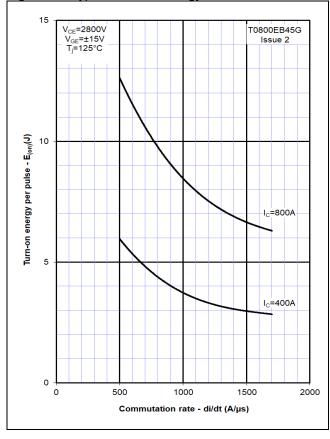


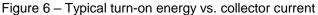


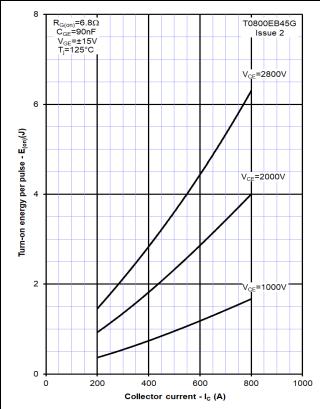
Figure 5 – Typical turn-off delay time vs. gate resistance













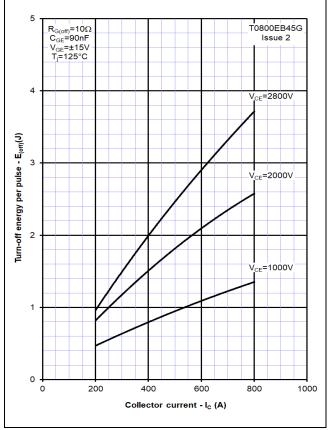
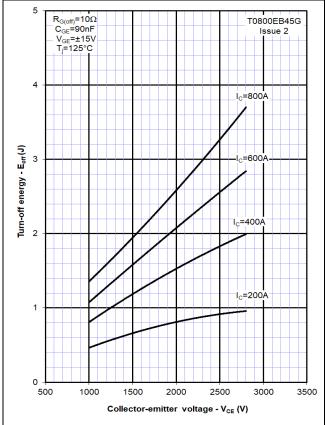




Figure 9 - Turn-off energy vs voltage



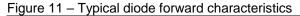




Figure 10 – Safe operating area (IGBT)

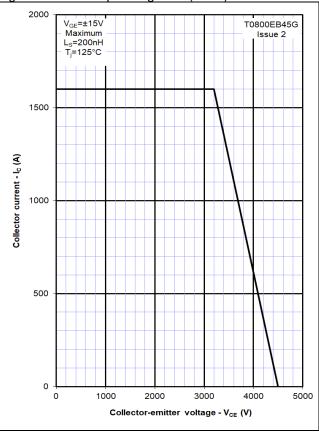
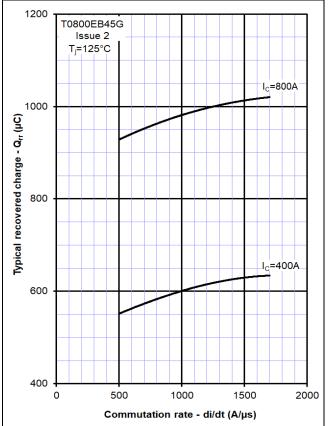


Figure 12 – Typical recovered charge



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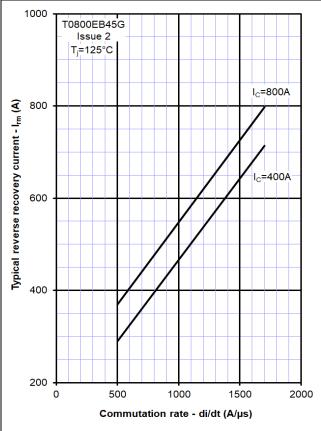


Figure 13 – Typical reverse recovery current

Figure 15 – Typical reverse recovery energy

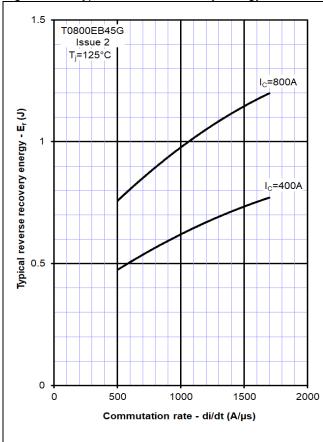


Figure 14 – Typical reverse recovery time

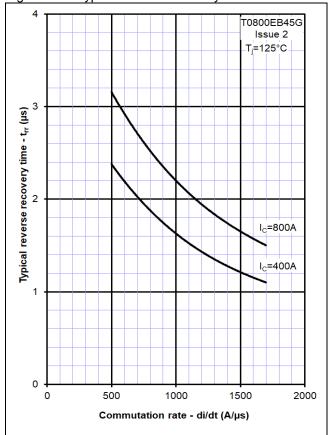


Figure 16 – Safe operating area (Diode)





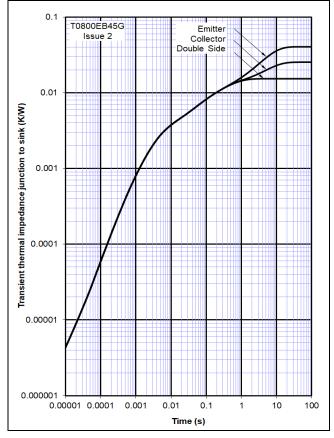
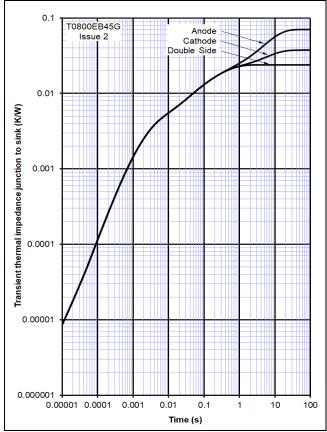


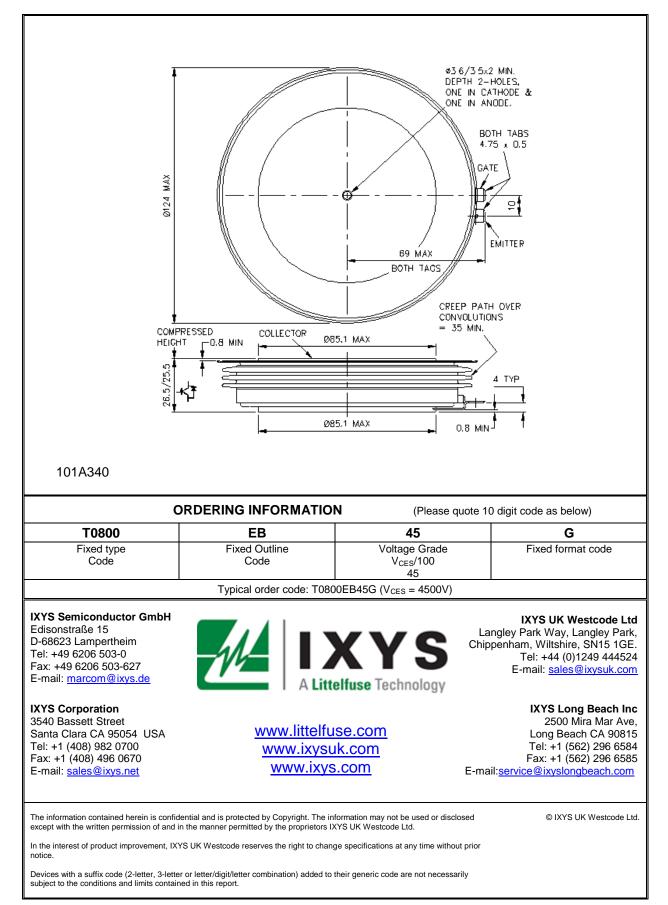
Figure 17 – Transient thermal impedance (IGBT)

Figure 18 - Transient thermal impedance (Diode)





Outline Drawing & Ordering Information





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